

Abstract of the Disclosure:

For the purpose of contact-connecting an electrical component, in particular a semiconductor component, on a substrate having a conductor structure, a joining temperature is chosen in such a way that the substrate, with a pressure being exerted on the electrical component, experiences a plastic deformation, with the result that the electrical component is pressed together with the conductor structure into the substrate in a positively locking manner. In order to produce the connection between the component and the substrate, use is preferably made of a thin diffusion solder layer which can be processed at temperatures lying below the melting point of the substrate.

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